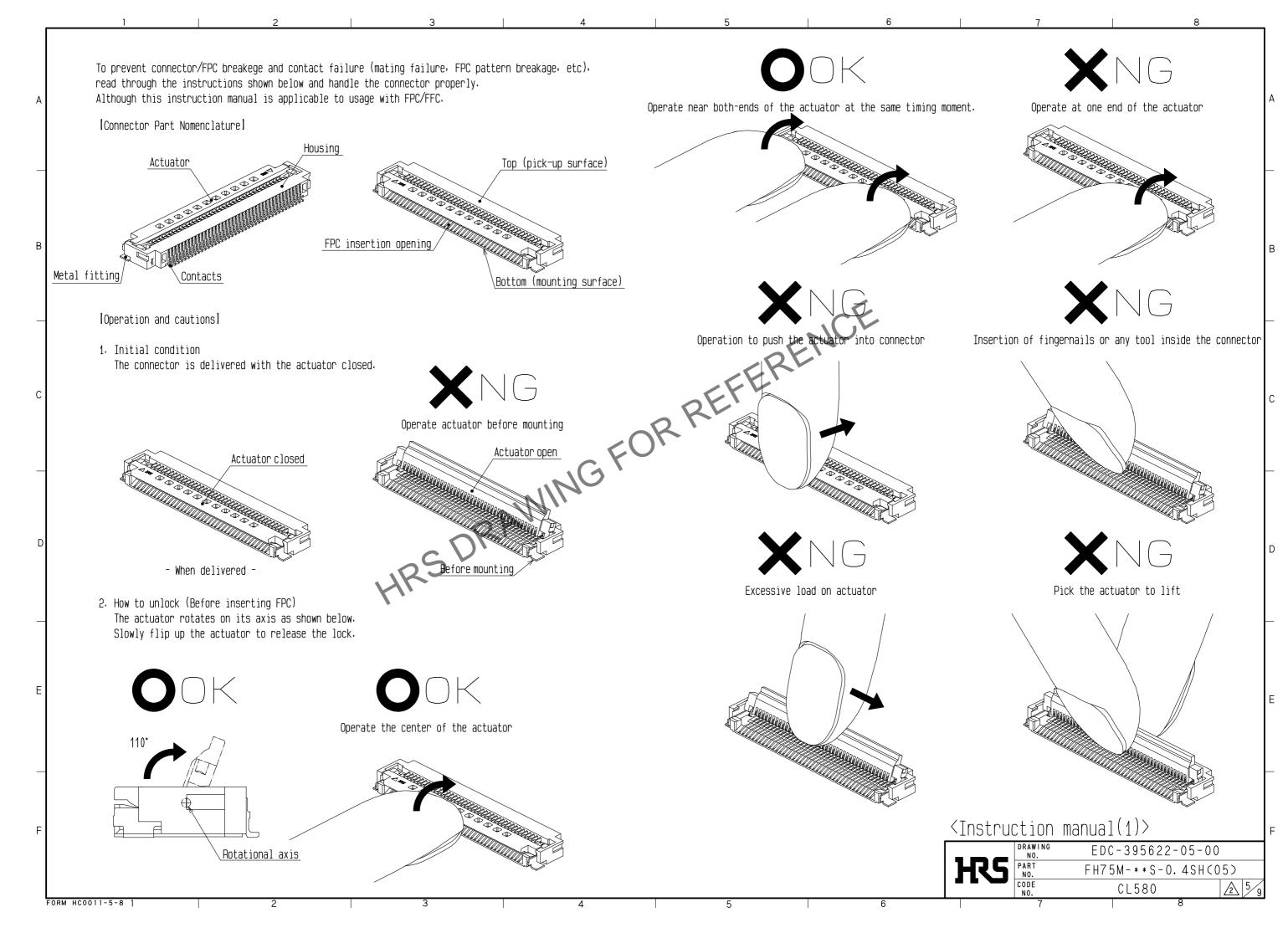
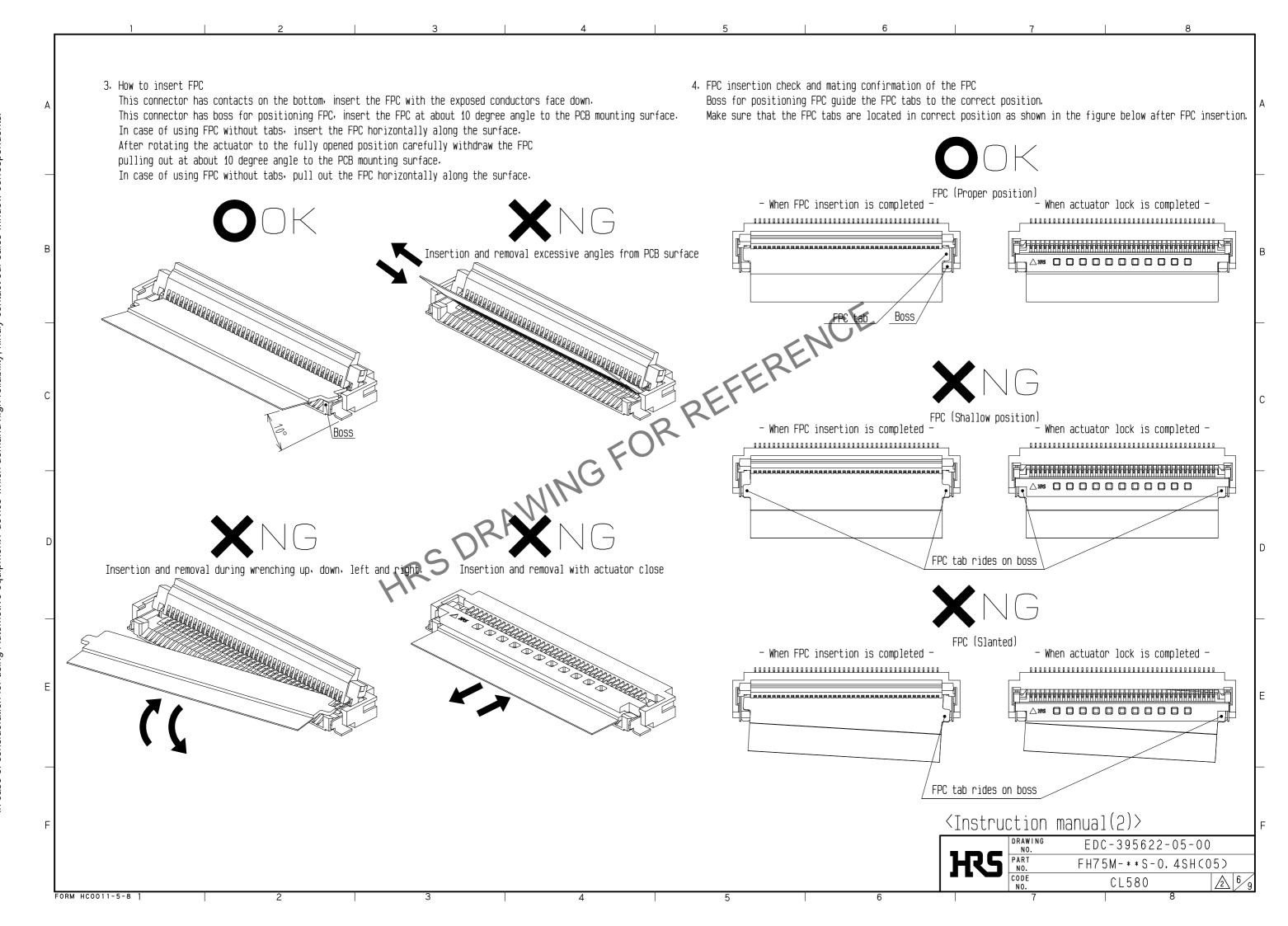


	Part No.	Code Number	Number of								Dimension of drawing for packing						
l			contacts	Α	В	С	D	E	F	G	Н	J	K	L	М	Р	Q
,	FH75M-80S-0.4SH(05)		80	36.2	31.6	32.47	34.45	36.2	34.0	34.0	32.4	26.2	56	52.4	37.6	57.4	61.4
2	FH75M-100S-0.4SH(05)	CL580-5306-0-05	100	44.2	39.6	40.47	42.45	44.2	42.0	42.0	40.4	34.2	72	68.4	45.6	73.4	77.4
<u> </u>	FH75M-120S-0.4SH(05)	CL580-5311-0-05	120	52.2	47.6	48.47	50.45	52.2	50.0	50.0	48.4	34.2	72	68.4	53.5	73.4	77.4
	FH75M-100S-0.4SH(05) FH75M-120S-0.4SH(05) **The products Please contac	without code num t Hirose for det	ster ar	e curr inform	ently	under	plannin	g. varia	tion.	RE							

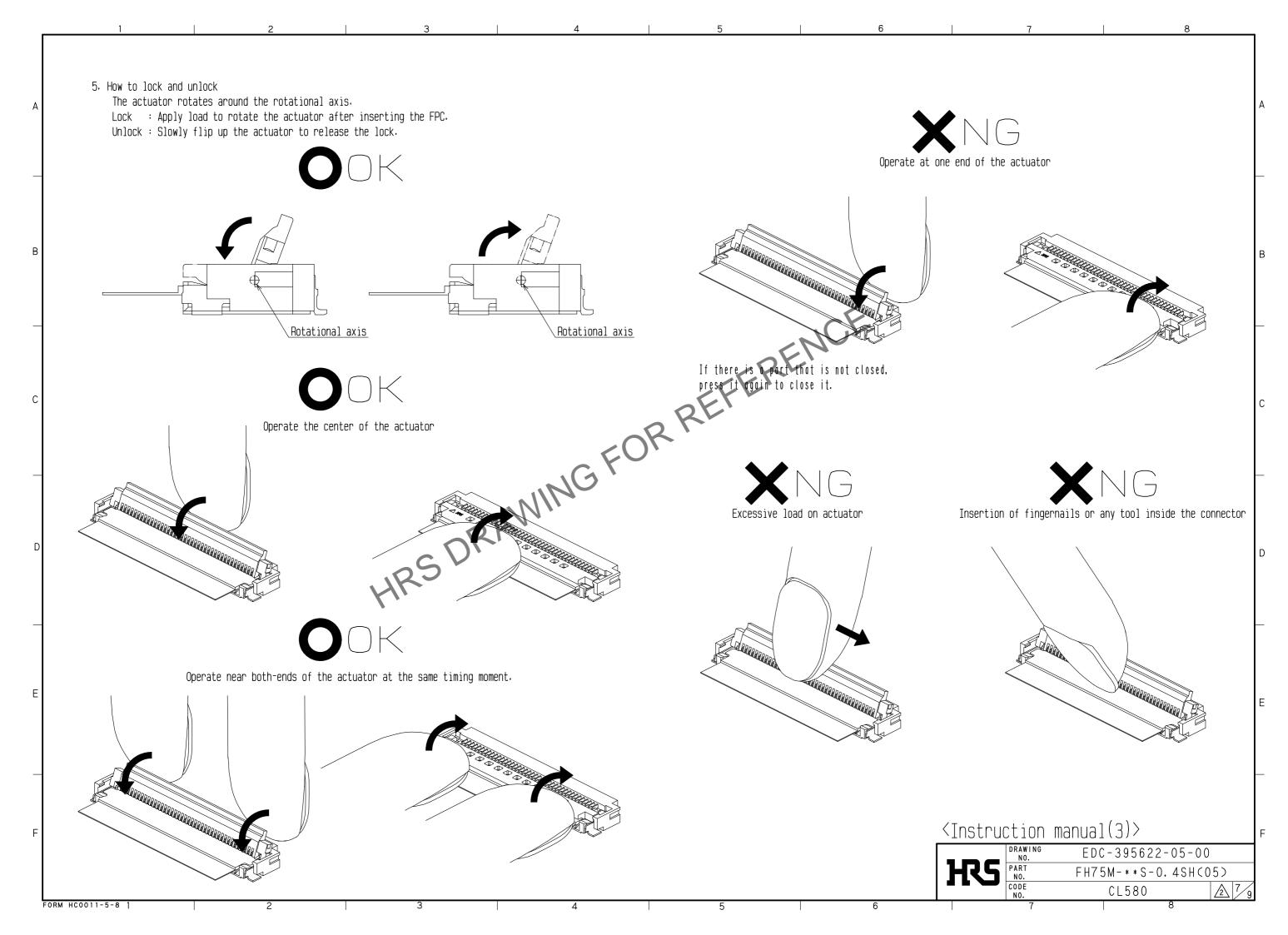
PART NO.
CODE NO. EDC-395622-05-00 FH75M-**S-0.4SH(05) 2 4 9 CL580

FORM HC0011-5-8 1 4

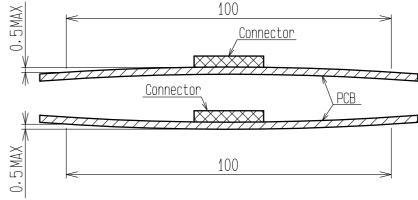








|Instructions for mounting on the PCB| | Instructions for PCB layout Please design a PCB layout not to apply load to connector and FPC. - Refer to recommended layouts for PCB, stencil pattern and FPC dimension. - When there is silk printing etc. on the bottom of the connector, [Cautions] please check the mounting condition before use. - When fixing FPC after FPC cabling, avoid pulling FPC, and route the wire FPC with slack. - Apply reflow temperature profile within the specified conditions. In this regard, the stiffener is parallel to the PCB. The mounting condition may change depending on the type of cream solder, manufacturer, PCB size. - Do not mount other components touching to the FPC underneath the FPC stiffener. Please check the mounting condition before use and conditions of other mounting parts. - Make adjustments with the FPC manufacturer for FPC bending performance and wire breakage. - Prevent warpage of PCB, the co-planarity of the connector is less than 0.1mm. - Keep spaces for the actuator movement and its operation for PCB design and component layout. but when the warpage of the PCB is large, soldering failure occurs. - Please contact Hirose incase you would like to use an FPC with a different dimension - When mounting on the flexible board, please make sure to put a stiffener or shape than recommended. on the backside of the flexible board. We recommend a glass epoxy material with the thickness of 0.3 mm min. - Do not add 0.5 N or greater external force when unreel or adsorb the connector etc, or it may get broken. | Instructions for PCB handling after mounting the connector Load applied to stiffener No load applied to stiffener Due to warpage of the PCB. load may be applied to the connector and it may be damaged. - ·Splitting a large PCB into several pieces ·Screwing the PCB During the handling described above, do not exert an excessive force on the PCB. Otherwise, the connector may become defective. -The warp of a 100 mm wide PCB should be 0.5 mm or less. The warp of PCB suffers stress on connector and the connector may become defective Stiffener 100 (horizental) 5 MAX Connector



Housing or parts interfering with the FPC



Load applied to FPC

Stiffener (Diagonally) [Instructions of hand soldering]

- Do not perform hand soldering with the FPC inserted into the connector.

- Do not apply excessive heat. And soldering iron must not touch connector except terminal leads area.

- Do not supply excessive solder (flux).

<Instruction manual(4)>

EDC-395622-05-00 FH75M-**S-0.4SH(05) CL580

FORM HC0011-5-8

[Recommended reflow temperature profile]

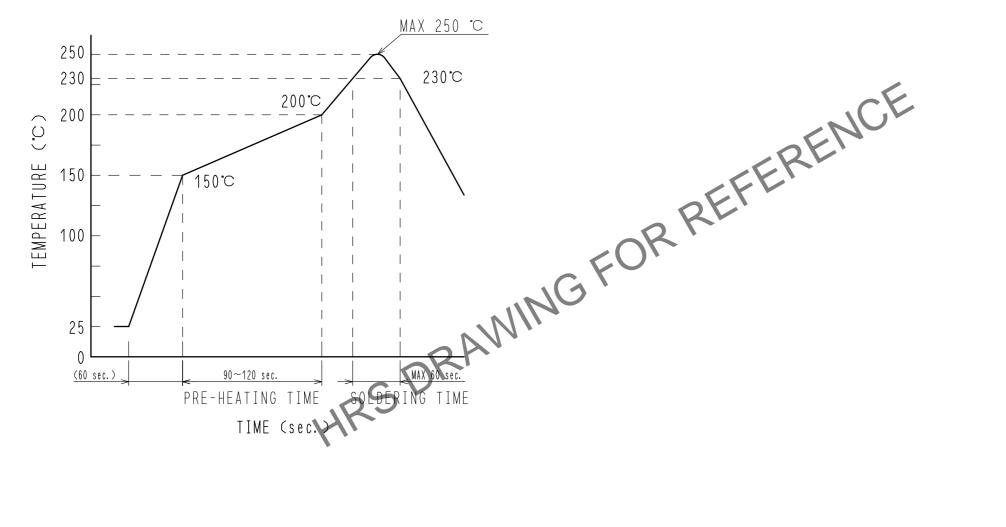
The temperatures mentioned above refer to the PCB surface temperature near the connector leads.

In individual applications the actual temperature may vary, depending on solder paste type volume/thickness and board size

depending on solder paste type volume/thickness and board size/thickness. Consult your solder paste and equipment manufacturer for specific recommendations.

-Reflow method:IR reflow

-Number of reflow cycles:2 cycles MAX.



PART FH75M-**S-0.4SH(05)

CODE NO. CL580

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FORM HC0011-5-8 1 2 3 4 5